



100% Material Declaration Data Sheet PQ160

PK165 (v1.2.1) October 19, 2006

Material Declaration Data Sheet

Average Weight: 5.8 g

Component	Substance Description	CAS# or Description	% of Component	Use in Product	Component Weight/ Substance Weight (in grams)	Component % of Total
Silicon Die					0.07366	1.27%
	Silicon	7440-21-3	100.00		0.07366	
Die Attach Material					0.00928	0.16%
	Silver	7440-22-4	78.00		0.0072384	
	Epoxy (EP)	Trade Secret	22.00		0.0020416	
Mold Compound					4.92304	84.88%
	Epoxy Resin (EP)	Trade Secret	9.00		0.4430736	
	Phenolic Resin	Trade Secret	7.00		0.3446128	
	Carbon Black	1333-86-4	0.50		0.0246152	
	Silica	60676-86-0	82.50		4.061508	
	Bismuth	7440-69-9	Max 1.00		0.0492304	
Leadframe					0.73486	12.67%
	Copper	7440-50-8	98.85		0.72640911	
	Chromium	7440-47-3	0.30		0.00220458	
	Tin	7440-31-5	0.25		0.00183715	
	Zinc	7440-66-6	0.60		0.00440916	
Leadframe Plating					0.00638	0.11%
	Silver	7440-22-4	100.00		0.00638	
Bond Wire					0.01392	0.24%
	Gold	7440-57-5	100.00		0.01392	
Ext. Plating					0.03886	0.67 %
	Tin	7440-31-5	85.00		0.033031	
	Lead	7439-92-1	15.00		0.005829	

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Revision History

The following table shows the revision history for this document.

Date	Revision	Revision
3/23/06	1.0	Initial release.
6/05/06	1.1	100% Material Declaration.
10/3/06	1.2	Updated component descriptions.
10/19/06	1.2.1	Editorial change; corrected typo in Substance Description.